

High Volume Industry-Standard Packages

SOT25



3.0 x 2.8 x 1.15

SOD123F/DO-219AA



3.5 x 1.8 x 0.98 /
3.8 x 1.9 x 1.18

SOT223



6.5 x 7.0 x 1.6

SMA



5.2 x 2.6 x 2.2

SMAF



5.2 x 2.6 x 1.0

SMB



5.3 x 3.64 x 2.25

SMC



6.85 x 5.9 x 2.25

SO-8



4.9 x 6.0 x 1.5

MSOP8



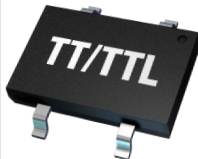
3.0 x 4.9 x 1.1

SO-14EP



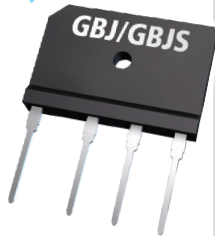
8.65 x 6.0 x 1.75

TT/TTL



9.6 x 9.9 x 1.5

GBJ/GBJS



30 x 4.6 x 20

SMD



5.0 x 3.2 x 1.2

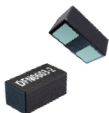
LQFP128-EP



14 x 14 x 1.6

High-Performance Small Form Factor Power Packages

X3-DFN0603-2



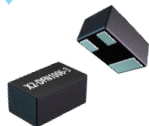
0.62 x 0.32 x 0.3

X2-DFN0604-3



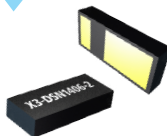
0.6 x 0.4 x 0.36

X2-DFN1006-3



1.0 x 0.6 x 0.3

X3-DSN1406-2



1.4 x 0.6 x 0.25

PowerDI®323



2.5 x 1.25 x 0.65

PowerDI®123



3.7 x 1.78 x 0.98

U-DFN2020-6



2.0 x 2.0 x 0.6

PowerDI®3333-8



3.3 x 3.3 x 0.8

PowerDI®5



6.51 x 3.97 x 1.1

PowerDI®5060-8



5.15 x 6.15 x 1.05

PowerDI®8080-5



8.0 x 7.95 x 1.6

PowerDI®1012



9.9 x 11.68 x 2.3

Thermally efficient underside heat pads provide superior thermal dissipation to reduce cooling cost and bring improved reliability and system stability.

Compact size increases current density to drastically reduce board real estate and reduce design size.



Application Note:
Understanding
Thermal Resistance
in the Real World